

## Serial I<sup>2</sup>C EEPROM in DFN5 package





# Target applications DFN5 package

Drones



Headsets



Industrial  
IoT



Smart medical  
devices



Designed for applications where **space and weight constraints** and **manufacturing robustness** are key factors



# DFN5 package features

**The DFN5 package offers significant improvements vs. DFN8**



**Other package names  
UFDFPN5\* or MLP5**

**\* UFDFPN: Ultra-thin Fine-pitch Dual Flat Package No lead**

Features	DFN5	DFN8
Package size	1.4 x 1.7 mm	2 x 3 mm
Thickness	0.55 mm	0.55 mm
Weight	7 mg	16 mg
Pin count	5 pin	8 pin
Pin type	Leadless	Leadless
Solder pitch	0.4 mm	0.5 mm

Package information and soldering guidelines available in [\*\*TN1171\*\*](#)



# DFN5 package benefits

Features	Benefits
Wide I <sup>2</sup> C portfolio Available in 2, 4, 8, 16, 32, 64, 128 and 256 Kbits	Easy upgrade thanks to same footprint for all densities
Package size: 1.4 x 1.7 mm	Minimize PCB footprint and gain at least 60% space versus DFN8
5 pin count and no leads	Reduce soldering budget and wire routing on PCB
Weight: 7 mg	Gain on application weight
Robust molded package & 0.4 mm pitch	Small package with easy handling and mounting
ECOPACK2 <sup>®</sup>	RoHS-compliant and halogen-free




# I<sup>2</sup>C EEPROM DFN5 Portfolio

UFDFPN5 – MLP5

## I<sup>2</sup>C EEPROM in DFN5 package offers

- Reduced PCB footprint
- Reduced application weight
- Easy handling and manufacturing robustness

 Click on <b>product name</b> to download the Datasheet	Memory density (Kbits)	Dimension (X/Y) (mm)		Profile (typ.) (mm)	Number of pins	Weight (mg)
<a href="#">M24C02-FMH6TG</a>	2	1.7	1.4	0.55	5	7
<a href="#">M24C04-FMH6TG</a>	4					
<a href="#">M24C08-FMH6TG</a>	8					
<a href="#">M24C16-FMH6TG</a>	16					
<a href="#">M24C32-FMH6TG</a>	32					
<a href="#">M24C64-FMH6TG</a>	64					
<a href="#">M24128-BFMH6TG</a>	128					
<a href="#">M24256E-FMH6TG</a>	256					



# I<sup>2</sup>C EEPROM in DFN5 package summary

Designed for small & light modules where robustness is a key factor

- Wide I<sup>2</sup>C portfolio up to 256 Kbits
- Robust ROHS and lead-free package
- Samples available now

- Request free samples or buy from [e-store](#)
- Check out the [DFN5 webpage](#)
- Prototype with [X-NUCLEO-EEPRMA2 shield](#)
- IBIS & soldering guidelines available on [st.com](#)

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